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			Application Number	10/670,291	
			Confirmation Number	6427	
			Filing Date	September 26, 2003	
			First Named Inventor	Miwa KOZAWA et al.	
			Art Unit	1756	
Examiner Name	Daborah Chacko-Davis				
Attorney Docket Number	031181				
Sheet	1	of	1		

U.S. PATENT DOCUMENTS					
Examiner Initials*	Cite No. ¹	Document Number		Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document
		Number	Kind Code ² (if known)		
		US			
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NON PATENT LITERATURE DOCUMENTS				
Examiner Initials*	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city, and/or country where published.		Translation ⁶
/dcd/	1	TAKEO ISHIBASHI ET AL., Advanced Micro-Lithography Process with Chemical Shrink Technology, Japanese Journal of Applied Physics Vol. 40 (2001) pp. 419-425		
/dcd/	2	MAMORU TERA I ET AL., Below 70-nm Contact Hole Pattern with RELACS Process on ArF Resist, Advances in Resist Technology and Processing XX, Therodore H. Fedynyshyn, Editor, Proceedings of SPIE Vol. 5039 (2003)		
/dcd/	3	MAMORU TERA I ET AL., Newly Developed Resolution Enhancement Lithography Assisted by Chemical Shrink Process and Materials for Next-Generation Devices, Japanese Journal of Applied Physics Vol. 45, No. 6B (2006) pp. 5354-5358		

Examiner Signature	/Daborah Chacko-Davis/	Date Considered	10/30/2007
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